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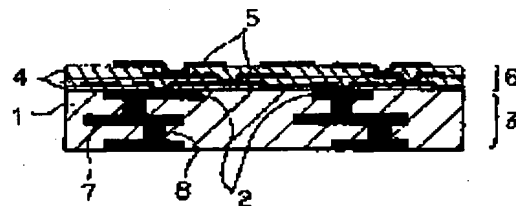
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(54) MULTI-LAYER WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a multilayer wiring board in which the adhesion between a multilayer wiring layer formed by a build-up method and a core board is improved, and high-density wiring is realized.

SOLUTION: An insulation substrate 1 on which at least two kinds of polymerization initiators whose half-life temperature for one minute is different by 10° C or more are mixed, and a mixture containing ceramic powder is supposed to a thermosetting treatment composed of two processes, to form a recession and protrusion having a surface roughness (Ra) of 0.1 μm or more. A wiring circuit layer 2 is adhered and formed on the substrate 1 to form a core substrate 3. A multilayer wiring layer 6 comprising an insulation layer 4 and a wiring circuit layer 5 is formed on the surface of the substrate 3 by a build-up method. As a result, the adhesion between the core substrate 3 and the multilayer wiring layer 6 can be improved.



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